



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Birang et al.
Serial No. : 10/721,769
Filed : November 24, 2003
Title : METHODS AND APPARATUS FOR POLISHING CONTROL

Art Unit : 2818
Examiner : David Nhu

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Applicants request consideration of the references listed on the attached PTO-1449 form. Under 37 C.F.R. § 1.98 (a)(2)(ii), only copies of foreign patent documents and/or non-patent literature are enclosed. Copies of any listed U.S. patents or U.S. patent application publications can be provided upon request.

This statement is being filed after a first Office action on the merits, but before receipt of a final Office action or a Notice of Allowance. A check for \$180 in payment of the late submission fee of §1.17(p) is enclosed. Please apply any other appropriate charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

Date:

September 7, 2005

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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

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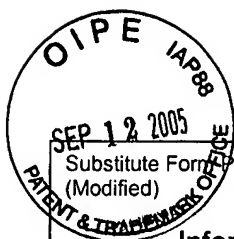
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09/13/2005 NNGUYEN1 00000028 10721769

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Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 05542-516001	Application No. 10/721,769
Information Disclosure Statement by Applicant (Use several sheets if necessary) (37 CFR §1.98(b))		Applicant Birang et al.	
		Filing Date November 24, 2003	Group Art Unit 2812

U.S. Patent Documents							
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA	5,081,796	01/1992	Schultz			
	AB	5,486,129	01/1996	Sandhu et al.			
	AC	5,658,183	08/1997	Sandhu et al.			
	AD	5,722,875	05/1998	Iwashita et al.			
	AE	5,730,642	03/1998	Sandhu et al.			
	AF	5,741,070	04/1998	Moslehi			
	AG	5,773,316	06/1998	Kurosaki et al.			
	AH	5,840,614	11/1998	Sim et al.			
	AI	5,985,094	11/1998	Mosca			
	AJ	6,159,073	12/2000	Wiswesser et al.			
	AK	6,413,145	07/2002	Pinson, II et al.			
	AL	6,422,927	07/2002	Zuniga			

Foreign Patent Documents or Published Foreign Patent Applications								
Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
	AM	DE 3801969 A	07/1989	DE			English Abstract	
	AN	EP 0879678 A	11/1998	EPO				
	AO	EP 0904895 A	03/1999	EPO				

Other Documents (include Author, Title, Date, and Place of Publication)		
Examiner Initial	Desig. ID	Document
	AP	Wijekoon et al., "Minimization of Metal Loss during Chemical Mechanical Planarization of Copper-Oxide and Copper - Low κ Damascene Structures", March 2002, Santa Clara, CA, 4 pp.
	AQ	Ravid et al., "Copper CMP Planarity Control Using ITM", 2000, Rehovoth, Israel, 7 pp.
	AR	Pan et al., "Copper CMP and Process Control", Final Paper submitted to CMP-MIC Conference, February 11-12, 1999, Santa Clara, CA and Cambridge, MA, 7 pp.
	AS	Zhang et al., "Automated Process Control of Within-Wafer and Wafer-to-Wafer Uniformity in Oxide CMP", March 2002, Santa Clara, CA, 6 pp.

Examiner Signature	Date Considered
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EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.